

Dell OptiPlex 3070 Micro

Service Manual



Notes, cautions, and warnings

 | **NOTE:** A NOTE indicates important information that helps you make better use of your product.

 | **CAUTION:** A CAUTION indicates either potential damage to hardware or loss of data and tells you how to avoid the problem.

 | **WARNING:** A WARNING indicates a potential for property damage, personal injury, or death.

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Working on your computer

Safety instructions

Use the following safety guidelines to protect your computer from potential damage and to ensure your personal safety. Unless otherwise noted, each procedure included in this document assumes that the following conditions exist:

- You have read the safety information that shipped with your computer.
- A component can be replaced or, if purchased separately, installed by performing the removal procedure in reverse order.

- ⚠ WARNING:** Disconnect all power sources before opening the computer cover or panels. After you finish working inside the computer, replace all covers, panels, and screws before connecting to the power source.
- ⚠ WARNING:** Before working inside your computer, read the safety information that shipped with your computer. For additional safety best practices information, see the [Regulatory Compliance Homepage](#)
- ⚠ CAUTION:** Many repairs may only be done by a certified service technician. You should only perform troubleshooting and simple repairs as authorized in your product documentation, or as directed by the online or telephone service and support team. Damage due to servicing that is not authorized by Dell is not covered by your warranty. Read and follow the safety instructions that came with the product.
- ⚠ CAUTION:** To avoid electrostatic discharge, ground yourself by using a wrist grounding strap or by periodically touching an unpainted metal surface at the same time as touching a connector on the back of the computer.
- ⚠ CAUTION:** Handle components and cards with care. Do not touch the components or contacts on a card. Hold a card by its edges or by its metal mounting bracket. Hold a component such as a processor by its edges, not by its pins.
- ⚠ CAUTION:** When you disconnect a cable, pull on its connector or on its pull-tab, not on the cable itself. Some cables have connectors with locking tabs; if you are disconnecting this type of cable, press in on the locking tabs before you disconnect the cable. As you pull connectors apart, keep them evenly aligned to avoid bending any connector pins. Also, before you connect a cable, ensure that both connectors are correctly oriented and aligned.
- ⓘ NOTE:** The color of your computer and certain components may appear differently than shown in this document.
- ⚠ CAUTION:** System will shut down if side covers are removed while the system is running. The system will not power on if the side cover is removed.
- ⚠ CAUTION:** System will shut down if side covers are removed while the system is running. The system will not power on if the side cover is removed.
- ⚠ CAUTION:** System will shut down if side covers are removed while the system is running. The system will not power on if the side cover is removed.

Before working inside your computer

To avoid damaging your computer, perform the following steps before you begin working inside the computer.

- 1 Ensure that you follow the [Safety Instruction](#).
- 2 Ensure that your work surface is flat and clean to prevent the computer cover from being scratched.
- 3 Turn off your computer.
- 4 Disconnect all network cables from the computer.

⚠ CAUTION: To disconnect a network cable, first unplug the cable from your computer and then unplug the cable from the network device.

- 5 Disconnect your computer and all attached devices from their electrical outlets.

6 Press and hold the power button while the computer is unplugged to ground the system board.

NOTE: To avoid electrostatic discharge, ground yourself by using a wrist grounding strap or by periodically touching an unpainted metal surface at the same time as touching a connector on the back of the computer.

Safety precautions

The safety precautions chapter details the primary steps to be taken before performing any disassembly instructions.

Observe the following safety precautions before you perform any installation or break/fix procedures involving disassembly or reassembly:

- Turn off the system and all attached peripherals.
- Disconnect the system and all attached peripherals from AC power.
- Disconnect all network cables, telephone, and telecommunications lines from the system.
- Use an ESD field service kit when working inside any tabletnotebookdesktop to avoid electrostatic discharge (ESD) damage.
- After removing any system component, carefully place the removed component on an anti-static mat.
- Wear shoes with non-conductive rubber soles to reduce the chance of getting electrocuted.

Standby power

Dell products with standby power must be unplugged before you open the case. Systems that incorporate standby power are essentially powered while turned off. The internal power enables the system to be remotely turned on (wake on LAN) and suspended into a sleep mode and has other advanced power management features.

Unplugging, pressing and holding the power button for 15 seconds should discharge residual power in the system board. Remove the battery from portabletabletsnotebooks.

Bonding

Bonding is a method for connecting two or more grounding conductors to the same electrical potential. This is done through the use of a field service electrostatic discharge (ESD) kit. When connecting a bonding wire, ensure that it is connected to bare metal and never to a painted or non-metal surface. The wrist strap should be secure and in full contact with your skin, and ensure that you remove all jewelry such as watches, bracelets, or rings prior to bonding yourself and the equipment.

Electrostatic discharge—ESD protection

ESD is a major concern when you handle electronic components, especially sensitive components such as expansion cards, processors, memory DIMMs, and system boards. Very slight charges can damage circuits in ways that may not be obvious, such as intermittent problems or a shortened product life span. As the industry pushes for lower power requirements and increased density, ESD protection is an increasing concern.

Due to the increased density of semiconductors used in recent Dell products, the sensitivity to static damage is now higher than in previous Dell products. For this reason, some previously approved methods of handling parts are no longer applicable.

Two recognized types of ESD damage are catastrophic and intermittent failures.

- **Catastrophic** – Catastrophic failures represent approximately 20 percent of ESD-related failures. The damage causes an immediate and complete loss of device functionality. An example of catastrophic failure is a memory DIMM that has received a static shock and immediately generates a "No POST/No Video" symptom with a beep code emitted for missing or nonfunctional memory.
- **Intermittent** – Intermittent failures represent approximately 80 percent of ESD-related failures. The high rate of intermittent failures means that most of the time when damage occurs, it is not immediately recognizable. The DIMM receives a static shock, but the tracing is merely weakened and does not immediately produce outward symptoms related to the damage. The weakened trace may take weeks or months to melt, and in the meantime may cause degradation of memory integrity, intermittent memory errors, etc.

The more difficult type of damage to recognize and troubleshoot is the intermittent (also called latent or "walking wounded") failure.

Perform the following steps to prevent ESD damage:

- Use a wired ESD wrist strap that is properly grounded. The use of wireless anti-static straps is no longer allowed; they do not provide adequate protection. Touching the chassis before handling parts does not ensure adequate ESD protection on parts with increased sensitivity to ESD damage.
- Handle all static-sensitive components in a static-safe area. If possible, use anti-static floor pads and workbench pads.
- When unpacking a static-sensitive component from its shipping carton, do not remove the component from the anti-static packing material until you are ready to install the component. Before unwrapping the anti-static packaging, ensure that you discharge static electricity from your body.
- Before transporting a static-sensitive component, place it in an anti-static container or packaging.

ESD field service kit

The unmonitored Field Service kit is the most commonly used service kit. Each Field Service kit includes three main components: anti-static mat, wrist strap, and bonding wire.

Components of an ESD field service kit

The components of an ESD field service kit are:

- **Anti-Static Mat** – The anti-static mat is dissipative and parts can be placed on it during service procedures. When using an anti-static mat, your wrist strap should be snug and the bonding wire should be connected to the mat and to any bare metal on the system being worked on. Once deployed properly, service parts can be removed from the ESD bag and placed directly on the mat. ESD-sensitive items are safe in your hand, on the ESD mat, in the system, or inside a bag.
- **Wrist Strap and Bonding Wire** – The wrist strap and bonding wire can be either directly connected between your wrist and bare metal on the hardware if the ESD mat is not required, or connected to the anti-static mat to protect hardware that is temporarily placed on the mat. The physical connection of the wrist strap and bonding wire between your skin, the ESD mat, and the hardware is known as bonding. Use only Field Service kits with a wrist strap, mat, and bonding wire. Never use wireless wrist straps. Always be aware that the internal wires of a wrist strap are prone to damage from normal wear and tear, and must be checked regularly with a wrist strap tester in order to avoid accidental ESD hardware damage. It is recommended to test the wrist strap and bonding wire at least once per week.
- **ESD Wrist Strap Tester** – The wires inside of an ESD strap are prone to damage over time. When using an unmonitored kit, it is a best practice to regularly test the strap prior to each service call, and at a minimum, test once per week. A wrist strap tester is the best method for doing this test. If you do not have your own wrist strap tester, check with your regional office to find out if they have one. To perform the test, plug the wrist-strap's bonding-wire into the tester while it is strapped to your wrist and push the button to test. A green LED is lit if the test is successful; a red LED is lit and an alarm sounds if the test fails.
- **Insulator Elements** – It is critical to keep ESD sensitive devices, such as plastic heat sink casings, away from internal parts that are insulators and often highly charged.
- **Working Environment** – Before deploying the ESD Field Service kit, assess the situation at the customer location. For example, deploying the kit for a server environment is different than for a desktop or portable environment. Servers are typically installed in a rack within a data center; desktops or portables are typically placed on office desks or cubicles. Always look for a large open flat work area that is free of clutter and large enough to deploy the ESD kit with additional space to accommodate the type of system that is being repaired. The workspace should also be free of insulators that can cause an ESD event. On the work area, insulators such as Styrofoam and other plastics should always be moved at least 12 inches or 30 centimeters away from sensitive parts before physically handling any hardware components.
- **ESD Packaging** – All ESD-sensitive devices must be shipped and received in static-safe packaging. Metal, static-shielded bags are preferred. However, you should always return the damaged part using the same ESD bag and packaging that the new part arrived in. The ESD bag should be folded over and taped shut and all the same foam packing material should be used in the original box that the new part arrived in. ESD-sensitive devices should be removed from packaging only at an ESD-protected work surface, and parts should never be placed on top of the ESD bag because only the inside of the bag is shielded. Always place parts in your hand, on the ESD mat, in the system, or inside an anti-static bag.
- **Transporting Sensitive Components** – When transporting ESD sensitive components such as replacement parts or parts to be returned to Dell, it is critical to place these parts in anti-static bags for safe transport.

ESD protection summary

It is recommended that all field service technicians use the traditional wired ESD grounding wrist strap and protective anti-static mat at all times when servicing Dell products. In addition, it is critical that technicians keep sensitive parts separate from all insulator parts while performing service and that they use anti-static bags for transporting sensitive components.

Transporting sensitive components

When transporting ESD sensitive components such as replacement parts or parts to be returned to Dell, it is critical to place these parts in anti-static bags for safe transport.

Lifting equipment

Adhere to the following guidelines when lifting heavy weight equipment:

 **CAUTION: Do not lift greater than 50 pounds. Always obtain additional resources or use a mechanical lifting device.**

- 1 Get a firm balanced footing. Keep your feet apart for a stable base, and point your toes out.
- 2 Tighten stomach muscles. Abdominal muscles support your spine when you lift, offsetting the force of the load.
- 3 Lift with your legs, not your back.
- 4 Keep the load close. The closer it is to your spine, the less force it exerts on your back.
- 5 Keep your back upright, whether lifting or setting down the load. Do not add the weight of your body to the load. Avoid twisting your body and back.
- 6 Follow the same techniques in reverse to set the load down.

After working inside your computer

After you complete any replacement procedure, ensure that you connect any external devices, cards, and cables before turning on your computer.

- 1 Connect any telephone or network cables to your computer.

 **CAUTION: To connect a network cable, first plug the cable into the network device and then plug it into the computer.**

- 2 Connect your computer and all attached devices to their electrical outlets.
- 3 Turn on your computer.
- 4 If required, verify that the computer works correctly by running **ePSA diagnostics**.

Technology and components

This chapter details the technology and components available in the system.

Topics:

- [DDR4](#)
- [USB features](#)
- [USB Type-C](#)
- [Advantages of DisplayPort over USB Type-C](#)
- [HDMI 2.0](#)
- [Intel Optane memory](#)

DDR4

DDR4 (double data rate fourth generation) memory is a higher-speed successor to the DDR2 and DDR3 technologies and allows up to 512 GB in capacity, compared to the DDR3's maximum of 128 GB per DIMM. DDR4 synchronous dynamic random-access memory is keyed differently from both SDRAM and DDR to prevent the user from installing the wrong type of memory into the system.

DDR4 needs 20 percent less or just 1.2 volts, compared to DDR3 which requires 1.5 volts of electrical power to operate. DDR4 also supports a new, deep power-down mode that allows the host device to go into standby without needing to refresh its memory. Deep power-down mode is expected to reduce standby power consumption by 40 to 50 percent.

DDR4 Details

There are subtle differences between DDR3 and DDR4 memory modules, as listed below.

Key notch difference

The key notch on a DDR4 module is in a different location from the key notch on a DDR3 module. Both notches are on the insertion edge but the notch location on the DDR4 is slightly different, to prevent the module from being installed into an incompatible board or platform.

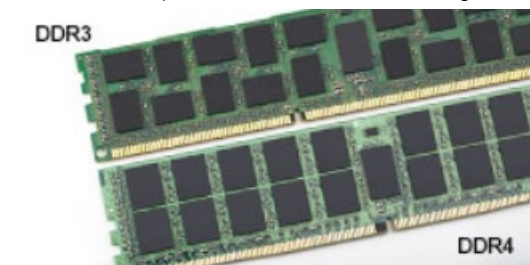


Figure 1. Notch difference

Increased thickness

DDR4 modules are slightly thicker than DDR3, to accommodate more signal layers.

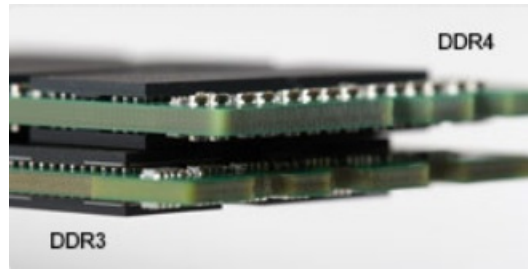


Figure 2. Thickness difference

Curved edge

DDR4 modules feature a curved edge to help with insertion and alleviate stress on the PCB during memory installation.



Figure 3. Curved edge

Memory Errors

Memory errors on the system display the new ON-FLASH-FLASH or ON-FLASH-ON failure code. If all memory fails, the LCD does not turn on. Troubleshoot for possible memory failure by trying known good memory modules in the memory connectors on the bottom of the system or under the keyboard, as in some portable systems.

NOTE: The DDR4 memory is imbedded in board and not a replaceable DIMM as shown and referred.

USB features

Universal Serial Bus, or USB, was introduced in 1996. It dramatically simplified the connection between host computers and peripheral devices like mice, keyboards, external drives, and printers.

Let's take a quick look on the USB evolution referencing to the table below.

Table 1. USB evolution

Type	Data Transfer Rate	Category	Introduction Year
USB 2.0	480 Mbps	High Speed	2000
USB 3.0/USB 3.1 Gen 1Port	5 Gbps	Super Speed	2010
USB 3.1 Gen 2	10 Gbps	Super Speed	2013

USB 3.0/USB 3.1 Gen 1 (SuperSpeed USB)

For years, the USB 2.0 has been firmly entrenched as the de facto interface standard in the PC world with about 6 billion devices sold, and yet the need for more speed grows by ever faster computing hardware and ever greater bandwidth demands. The USB 3.0/USB 3.1 Gen 1 finally has the answer to the consumers' demands with a theoretically 10 times faster than its predecessor. In a nutshell, USB 3.1 Gen 1 features are as follows:

- Higher transfer rates (up to 5 Gbps)
- Increased maximum bus power and increased device current draw to better accommodate power-hungry devices
- New power management features
- Full-duplex data transfers and support for new transfer types
- Backward USB 2.0 compatibility
- New connectors and cable

The topics below cover some of the most commonly asked questions regarding USB 3.0/USB 3.1 Gen 1.

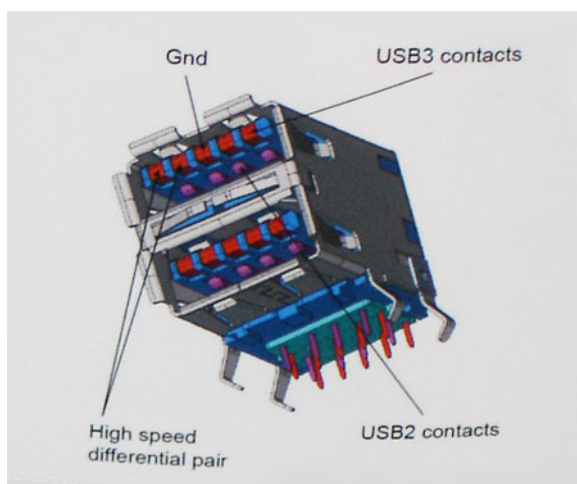


Speed

Currently, there are 3 speed modes defined by the latest USB 3.0/USB 3.1 Gen 1 specification. They are Super-Speed, Hi-Speed and Full-Speed. The new SuperSpeed mode has a transfer rate of 4.8Gbps. While the specification retains Hi-Speed, and Full-Speed USB mode, commonly known as USB 2.0 and 1.1 respectively, the slower modes still operate at 480Mbps and 12Mbps respectively and are kept to maintain backward compatibility.

USB 3.0/USB 3.1 Gen 1 achieves the much higher performance by the technical changes below:

- An additional physical bus that is added in parallel with the existing USB 2.0 bus (refer to the picture below).
- USB 2.0 previously had four wires (power, ground, and a pair for differential data); USB 3.0/USB 3.1 Gen 1 adds four more for two pairs of differential signals (receive and transmit) for a combined total of eight connections in the connectors and cabling.
- USB 3.0/USB 3.1 Gen 1 utilizes the bidirectional data interface, rather than USB 2.0's half-duplex arrangement. This gives a 10-fold increase in theoretical bandwidth.



With today's ever increasing demands placed on data transfers with high-definition video content, terabyte storage devices, high megapixel count digital cameras etc., USB 2.0 may not be fast enough. Furthermore, no USB 2.0 connection could ever come close to the 480Mbps

theoretical maximum throughput, making data transfer at around 320Mbps (40MB/s) — the actual real-world maximum. Similarly, USB 3.0/USB 3.1 Gen 1 connections will never achieve 4.8Gbps. We will likely see a real-world maximum rate of 400MB/s with overheads. At this speed, USB 3.0/USB 3.1 Gen 1 is a 10x improvement over USB 2.0.

Applications

USB 3.0/USB 3.1 Gen 1 opens up the laneways and provides more headroom for devices to deliver a better overall experience. Where USB video was barely tolerable previously (both from a maximum resolution, latency, and video compression perspective), it's easy to imagine that with 5-10 times the bandwidth available, USB video solutions should work that much better. Single-link DVI requires almost 2Gbps throughput. Where 480Mbps was limiting, 5Gbps is more than promising. With its promised 4.8Gbps speed, the standard will find its way into some products that previously weren't USB territory, like external RAID storage systems.

Listed below are some of the available SuperSpeed USB 3.0/USB 3.1 Gen 1 products:

- External Desktop USB 3.0/USB 3.1 Gen 1 Hard Drives
- Portable USB 3.0/USB 3.1 Gen 1 Hard Drives
- USB 3.0/USB 3.1 Gen 1 Drive Docks & Adapters
- USB 3.0/USB 3.1 Gen 1 Flash Drives & Readers
- USB 3.0/USB 3.1 Gen 1 Solid-state Drives
- USB 3.0/USB 3.1 Gen 1 RAIDs
- Optical Media Drives
- Multimedia Devices
- Networking
- USB 3.0/USB 3.1 Gen 1 Adapter Cards & Hubs

Compatibility

The good news is that USB 3.0/USB 3.1 Gen 1 has been carefully planned from the start to peacefully co-exist with USB 2.0. First of all, while USB 3.0/USB 3.1 Gen 1 specifies new physical connections and thus new cables to take advantage of the higher speed capability of the new protocol, the connector itself remains the same rectangular shape with the four USB 2.0 contacts in the exact same location as before. Five new connections to carry receive and transmitted data independently are present on USB 3.0/USB 3.1 Gen 1 cables and only come into contact when connected to a proper SuperSpeed USB connection.

Windows 8/10 will be bringing native support for USB 3.1 Gen 1 controllers. This is in contrast to previous versions of Windows, which continue to require separate drivers for USB 3.0/USB 3.1 Gen 1 controllers.

Microsoft announced that Windows 7 would have USB 3.1 Gen 1 support, perhaps not on its immediate release, but in a subsequent Service Pack or update. It is not out of the question to think that following a successful release of USB 3.0/USB 3.1 Gen 1 support in Windows 7, SuperSpeed support would trickle down to Vista. Microsoft has confirmed this by stating that most of their partners share the opinion that Vista should also support USB 3.0/USB 3.1 Gen 1.

USB Type-C

USB Type-C is a new, tiny physical connector. The connector itself can support various exciting new USB standards like USB 3.1 and USB power delivery (USB PD).

Alternate Mode

USB Type-C is a new connector standard that is very small. It is about a third the size of an old USB Type-A plug. This is a single connector standard that every device should be able to use. USB Type-C ports can support a variety of different protocols using “alternate modes,” which allows you to have adapters that can output HDMI, VGA, DisplayPort, or other types of connections from that single USB port

USB Power Delivery

The USB PD specification is also closely intertwined with USB Type-C. Currently, smartphones, tablets, and other mobile devices often use a USB connection to charge. A USB 2.0 connection provides up to 2.5 watts of power — that'll charge your phone, but that's about it. A laptop might require up to 60 watts, for example. The USB Power Delivery specification ups this power delivery to 100 watts. It's bi-directional, so a device can either send or receive power. And this power can be transferred at the same time the device is transmitting data across the connection.

This could spell the end of all those proprietary laptop charging cables, with everything charging via a standard USB connection. You could charge your laptop from one of those portable battery packs you charge your smartphones and other portable devices from today. You could plug your laptop into an external display connected to a power cable, and that external display would charge your laptop as you used it as an external display — all via the one little USB Type-C connection. To use this, the device and the cable have to support USB Power Delivery. Just having a USB Type-C connection doesn't necessarily mean they do.

USB Type-C and USB 3.1

USB 3.1 is a new USB standard. USB 3's theoretical bandwidth is 5 Gbps same as of USB 3.1 Gen 1, while USB 3.1 Gen 2's bandwidth is 10 Gbps. That's double the bandwidth, as fast as a first-generation Thunderbolt connector. USB Type-C isn't the same thing as USB 3.1. USB Type-C is just a connector shape, and the underlying technology could just be USB 2 or USB 3.0. In fact, Nokia's N1 Android tablet uses a USB Type-C connector, but underneath it's all USB 2.0 — not even USB 3.0. However, these technologies are closely related.

Advantages of DisplayPort over USB Type-C

- Full DisplayPort audio/video (A/V) performance (up to 4K at 60Hz)
- Reversible plug orientation and cable direction
- Backwards compatibility to VGA, DVI with adaptors
- SuperSpeed USB (USB 3.1) data
- Supports HDMI 2.0a and is backwards compatible with previous versions

HDMI 2.0

This topic explains the HDMI 2.0 and its features along with the advantages.

HDMI (High-Definition Multimedia Interface) is an industry-supported, uncompressed, all-digital audio/video interface. HDMI provides an interface between any compatible digital audio/video source, such as a DVD player, or A/V receiver and a compatible digital audio and/or video monitor, such as a digital TV (DTV). The intended applications for HDMI TVs, and DVD players. The primary advantage is cable reduction and content protection provisions. HDMI supports standard, enhanced, or high-definition video, plus multichannel digital audio on a single cable.

HDMI 2.0 Features

- **HDMI Ethernet Channel** - Adds high-speed networking to an HDMI link, allowing users to take full advantage of their IP-enabled devices without a separate Ethernet cable
- **Audio Return Channel** - Allows an HDMI-connected TV with a built-in tuner to send audio data "upstream" to a surround audio system, eliminating the need for a separate audio cable
- **3D** - Defines input/output protocols for major 3D video formats, paving the way for true 3D gaming and 3D home theater applications
- **Content Type** - Real-time signaling of content types between display and source devices, enabling a TV to optimize picture settings based on content type
- **Additional Color Spaces** - Adds support for additional color models used in digital photography and computer graphics
- **4K Support** - Enables video resolutions far beyond 1080p, supporting next-generation displays that will rival the Digital Cinema systems used in many commercial movie theaters

- **HDMI Micro Connector** - A new, smaller connector for phones and other portable devices, supporting video resolutions up to 1080p
- **Automotive Connection System** - New cables and connectors for automotive video systems, designed to meet the unique demands of the motoring environment while delivering true HD quality

Advantages of HDMI

- Quality HDMI transfers uncompressed digital audio and video for the highest, crispest image quality.
- Low -cost HDMI provides the quality and functionality of a digital interface while also supporting uncompressed video formats in a simple, cost-effective manner
- Audio HDMI supports multiple audio formats from standard stereo to multichannel surround sound
- HDMI combines video and multichannel audio into a single cable, eliminating the cost, complexity, and confusion of multiple cables currently used in A/V systems
- HDMI supports communication between the video source (such as a DVD player) and the DTV, enabling new functionality

Intel Optane memory

Intel Optane memory functions only as a storage accelerator. It neither replaces nor adds to the memory (RAM) installed on your computer.

NOTE: Intel Optane memory is supported on computers that meet the following requirements:

- 7th Generation or higher Intel Core i3/i5/i7 processor
- Windows 10 64-bit version 1607 or higher
- Intel Rapid Storage Technology driver version 15.9.1.1018 or higher

Table 2. Intel Optane memory specifications

Feature	Specifications
Interface	PCIe 3x2 NVMe 1.1
Connector	M.2 card slot (2230/2280)
Configurations supported	<ul style="list-style-type: none"> • 7th Generation or higher Intel Core i3/i5/i7 processor • Windows 10 64-bit version 1607 or higher • Intel Rapid Storage Technology driver version 15.9.1.1018 or higher
Capacity	32 GB

Enabling Intel Optane memory

- 1 On the taskbar, click the search box, and type "**Intel Rapid Storage Technology**".
- 2 Click **Intel Rapid Storage Technology**.
- 3 On the **Status** tab, click **Enable** to enable the Intel Optane memory.
- 4 On the warning screen, select a compatible fast drive, and then click **Yes** to continue enabling Intel Optane memory.
- 5 Click **Intel Optane memory > Reboot** to enable the Intel Optane memory.

NOTE: Applications may take up to three subsequent launches after enablement to see the full performance benefits.

Disabling Intel Optane memory

CAUTION: After disabling Intel Optane memory, do not uninstall the driver for Intel Rapid Storage Technology as it will result in a blue screen error. The Intel Rapid Storage Technology user interface can be removed without uninstalling the driver.

NOTE: Disabling Intel Optane memory is required before removing the SATA storage device, accelerated by the Intel Optane memory module, from the computer.

- 1 On the taskbar, click the search box, and then type "**Intel Rapid Storage Technology**".
- 2 Click **Intel Rapid Storage Technology**. The **Intel Rapid Storage Technology** window is displayed.
- 3 On the **Intel Optane memory** tab, click **Disable** to disable the Intel Optane memory.
- 4 Click **Yes** if you accept the warning.
The disabling progress is displayed.
- 5 Click **Reboot** to complete disabling Intel Optane memory and restart your computer.

Troubleshooting

Enhanced Pre-Boot System Assessment — ePSA diagnostics

The ePSA diagnostics (also known as system diagnostics) performs a complete check of your hardware. The ePSA is embedded with the BIOS and is launched by the BIOS internally. The embedded system diagnostics provides a set of options for particular devices or device groups allowing you to:

The ePSA diagnostics can be initiated by the FN+PWR buttons while powering on the computer.

- Run tests automatically or in an interactive mode
- Repeat tests
- Display or save test results
- Run thorough tests to introduce additional test options to provide extra information about the failed device(s)
- View status messages that inform you if tests are completed successfully
- View error messages that inform you of problems encountered during testing

① **NOTE: Some tests for specific devices require user interaction. Always ensure that you are present at the computer terminal when the diagnostic tests are performed.**

Running the ePSA Diagnostics

Invoke diagnostics boot by either of the methods that are suggested below:

- 1 Power on the computer.
- 2 As the computer boots, press the F12 key when the Dell logo is displayed.
- 3 In the boot menu screen, use Up/Down arrow key to select the **Diagnostics** option and then press **Enter**.

① **NOTE: The Enhanced Pre-boot System Assessment window displays, listing all devices detected in the computer. The diagnostics starts running the tests on all the detected devices.**

- 4 Press the arrow in the lower-right corner to go to the page listing.
The detected items are listed and tested.
- 5 To run a diagnostic test on a specific device, press Esc and click **Yes** to stop the diagnostic test.
- 6 Select the device from the left pane and click **Run Tests**.
- 7 If there are any issues, error codes are displayed.
Note the error code and contact Dell.
or
- 8 Shut down the computer.
- 9 Press and hold the Fn key, while pressing the power button, and then release both.
- 10 Repeat steps 3–7 above.

Diagnostics

The computer POST (Power On Self Test) ensures that it meets the basic computer requirements and the hardware is working appropriately before the boot process begins. If the computer passes the POST, the computer continues to start in a normal mode.

However, if the computer fails the POST, the computer emits a series of LED codes during the start-up. The system LED is integrated on the Power button.

The following table shows different light patterns and what they indicate.

Table 3. Power LED summary

Amber LED state	White LED state	System state	Notes
Off	Off	S4, S5	<ul style="list-style-type: none"> • Hibernate or Suspend to Disk (S4) • Power is off (S5)
Off	Blinking	S1, S3	System is in a low power state, either S1 or S3. This does not indicate a fault condition.
Previous State	Previous State	S3, no PWRGD_PS	This entry provides for the possibility of a delay from SLP_S3# active to PWRGD_PS inactive.
Blinking	Off	S0, no PWRGD_PS	Boot Failure - The computer is receiving electrical power, and power supplied by the power supply is normal. A device might be malfunctioning or incorrectly installed. Refer to the table below for Amber Blinking Pattern diagnostics suggestion and possible failures.
Steady	Off	S0, no PWRGD_PS, Code fetch = 0	Boot Failure - This is a system fault error condition, including the power supply. Only the +5VSB rail on the power supply is working correctly.
Off	Steady	S0, no PWRGD_PS, Code fetch = 1	This indicates that the host BIOS has started to execute and the LED register is now writable.

Table 4. Amber LED blinking failures

Amber LED state	White LED state	System state	Notes
2	1	Bad MBD	Bad MBD - Rows A, G, H, and J from table 12.4 of SIO Spec - Pre-Post indicators [40]
2	2	Bad MB, PSU or cabling	Bad MBD, PSU or PSU cabling - Rows B, C and D of table 12.4 SIO spec [40]
2	3	Bad MBD, DIMMS, or CPU	Bad MBD, DIMMS or CPU - Rows F and K from table 12.4 of SIO spec [40]
2	4	Bad coin cell	Bad coin cell - Row M of table 12.4 in SIO spec [40]

Table 5. States Under Host BIOS Control

Amber LED state	White LED state	System state	Notes
2	5	BIOS state 1	BIOS Post code (Old LED pattern 0001) Corrupt BIOS.
2	6	BIOS state 2	BIOS Post code (Old LED pattern 0010) CPU config or CPU failure.
2	7	BIOS state 3	BIOS Post code (Old LED pattern 0011) MEM config in process. Appropriate mem modules detected but failure has occurred.
3	1	BIOS state 4	BIOS Post code (Old LED pattern 0100) Combine PCI device config or failure with video sub sytem config or failure. BIOS to eliminate 0101 video code.
3	2	BIOS state 5	BIOS Post code (Old LED pattern 0110) Combine storage and USB config or failure. BIOS to eliminate 0111 USB code.
3	3	BIOS state 6	BIOS Post code (Old LED pattern 1000) MEM config, no memory detected.
3	4	BIOS state 7	BIOS Post code (Old LED pattern 1001) Fatal Motherboard error.
3	5	BIOS state 8	BIOS Post code (Old LED pattern 1010) Mem config, modules incompatible or invalid config.
3	6	BIOS state 9	BIOS Post code (Old LED pattern 1011) combine "Other pre-video activity and resource configuration codes. BIOS to eliminate 1100 code.
3	7	BIOS state 10	BIOS Post code (Old LED pattern 1110) Other pre-post activity, routine subsequent to video init.

Diagnostic error messages

Table 6. Diagnostic error messages

Error messages	Description
AUXILIARY DEVICE FAILURE	The touchpad or external mouse may be faulty. For an external mouse, check the cable connection. Enable the Pointing Device option in the System Setup program.
BAD COMMAND OR FILE NAME	Ensure that you have spelled the command correctly, put spaces in the proper place, and used the correct path name.

Error messages

Error messages	Description
CACHE DISABLED DUE TO FAILURE	The primary cache internal to the microprocessor has failed. Contact Dell
CD DRIVE CONTROLLER FAILURE	The optical drive does not respond to commands from the computer.
DATA ERROR	The hard drive cannot read the data.
DECREASING AVAILABLE MEMORY	One or more memory modules may be faulty or improperly seated. Reinstall the memory modules or, if necessary, replace them.
DISK C: FAILED INITIALIZATION	The hard drive failed initialization. Run the hard drive tests in Dell Diagnostics .
DRIVE NOT READY	The operation requires a hard drive in the bay before it can continue. Install a hard drive in the hard drive bay.
ERROR READING PCMCIA CARD	The computer cannot identify the ExpressCard. Reinsert the card or try another card.
EXTENDED MEMORY SIZE HAS CHANGED	The amount of memory recorded in non-volatile memory (NVRAM) does not match the memory module installed in the computer. Restart the computer. If the error appears again, Contact Dell
THE FILE BEING COPIED IS TOO LARGE FOR THE DESTINATION DRIVE	The file that you are trying to copy is too large to fit on the disk, or the disk is full. Try copying the file to a different disk or use a larger capacity disk.
A FILENAME CANNOT CONTAIN ANY OF THE FOLLOWING CHARACTERS: \ / : * ? " < > -	Do not use these characters in filenames.
GATE A20 FAILURE	A memory module may be loose. Reinstall the memory module or, if necessary, replace it.
GENERAL FAILURE	The operating system is unable to carry out the command. The message is usually followed by specific information. For example, <i>Printer out of paper</i> . Take the appropriate action.
HARD-DISK DRIVE CONFIGURATION ERROR	The computer cannot identify the drive type. Shut down the computer, remove the hard drive, and boot the computer from an optical drive. Then, shut down the computer, reinstall the hard drive, and restart the computer. Run the Hard Disk Drive tests in Dell Diagnostics .
HARD-DISK DRIVE CONTROLLER FAILURE 0	The hard drive does not respond to commands from the computer. Shut down the computer, remove the hard drive, and boot the computer from an optical drive. Then, shut down the computer, reinstall the hard drive, and restart the computer. If the problem persists, try another drive. Run the Hard Disk Drive tests in Dell Diagnostics .
HARD-DISK DRIVE FAILURE	The hard drive does not respond to commands from the computer. Shut down the computer, remove the hard drive, and boot the computer from an optical drive. Then, shut down the computer, reinstall the hard drive, and restart the computer. If the problem persists, try another drive. Run the Hard Disk Drive tests in Dell Diagnostics .
HARD-DISK DRIVE READ FAILURE	The hard drive may be defective. Shut down the computer, remove the hard drive, and boot the computer from an optical. Then, shut down the computer, reinstall the hard drive, and restart the

Error messages

Description

INSERT BOOTABLE MEDIA	computer. If the problem persists, try another drive. Run the Hard Disk Drive tests in Dell Diagnostics .
INVALID CONFIGURATION INFORMATION-PLEASE RUN SYSTEM SETUP PROGRAM	The operating system is trying to boot to non-bootable media, such as an optical drive. Insert bootable media.
KEYBOARD CLOCK LINE FAILURE	The system configuration information does not match the hardware configuration. The message is most likely to occur after a memory module is installed. Correct the appropriate options in the system setup program.
KEYBOARD CONTROLLER FAILURE	For external keyboards, check the cable connection. Run the Keyboard Controller test in Dell Diagnostics .
KEYBOARD DATA LINE FAILURE	For external keyboards, check the cable connection. Restart the computer, and avoid touching the keyboard or the mouse during the boot routine. Run the Keyboard Controller test in Dell Diagnostics .
KEYBOARD STUCK KEY FAILURE	For external keyboards, check the cable connection. Run the Keyboard Controller test in Dell Diagnostics .
LICENSED CONTENT IS NOT ACCESSIBLE IN MEDIADIRECT	For external keyboards or keypads, check the cable connection. Restart the computer, and avoid touching the keyboard or keys during the boot routine. Run the Stuck Key test in Dell Diagnostics .
MEMORY ADDRESS LINE FAILURE AT ADDRESS, READ VALUE EXPECTING VALUE	Dell MediaDirect cannot verify the Digital Rights Management (DRM) restrictions on the file, so the file cannot be played.
MEMORY ALLOCATION ERROR	A memory module may be faulty or improperly seated. Reinstall the memory module or, if necessary, replace it.
MEMORY DOUBLE WORD LOGIC FAILURE AT ADDRESS, READ VALUE EXPECTING VALUE	The software you are attempting to run is conflicting with the operating system, another program, or a utility. Shut down the computer, wait for 30 seconds, and then restart it. Run the program again. If the error message still appears, see the software documentation.
MEMORY ODD/EVEN LOGIC FAILURE AT ADDRESS, READ VALUE EXPECTING VALUE	A memory module may be faulty or improperly seated. Reinstall the memory module or, if necessary, replace it.
MEMORY WRITE/READ FAILURE AT ADDRESS, READ VALUE EXPECTING VALUE	A memory module may be faulty or improperly seated. Reinstall the memory module or, if necessary, replace it.
NO BOOT DEVICE AVAILABLE	A memory module may be faulty or improperly seated. Reinstall the memory module or, if necessary, replace it.
NO BOOT SECTOR ON HARD DRIVE	The computer cannot find the hard drive. If the hard drive is your boot device, ensure that the drive is installed, properly seated, and partitioned as a boot device.
NO TIMER TICK INTERRUPT	The operating system may be corrupted. Contact Dell .
NOT ENOUGH MEMORY OR RESOURCES. EXIT SOME PROGRAMS AND TRY AGAIN	A chip on the system board may be malfunctioning. Run the System Set tests in Dell Diagnostics .
OPERATING SYSTEM NOT FOUND	You have too many programs open. Close all windows and open the program that you want to use.
OPTIONAL ROM BAD CHECKSUM	Reinstall the operating system. If the problem persists, Contact Dell .
	The optional ROM has failed. Contact Dell .

Error messages	Description
SECTOR NOT FOUND	The operating system cannot locate a sector on the hard drive. You may have a defective sector or corrupted File Allocation Table (FAT) on the hard drive. Run the Windows error-checking utility to check the file structure on the hard drive. See Windows Help and Support for instructions (click Start > Help and Support). If a large number of sectors are defective, back up the data (if possible), and then format the hard drive.
SEEK ERROR	The operating system cannot find a specific track on the hard drive.
SHUTDOWN FAILURE	A chip on the system board may be malfunctioning. Run the System Set tests in Dell Diagnostics . If the message reappears, Contact Dell .
TIME-OF-DAY CLOCK LOST POWER	System configuration settings are corrupted. Connect your computer to an electrical outlet to charge the battery. If the problem persists, try to restore the data by entering the System Setup program, then immediately exit the program. If the message reappears, Contact Dell .
TIME-OF-DAY CLOCK STOPPED	The reserve battery that supports the system configuration settings may require recharging. Connect your computer to an electrical outlet to charge the battery. If the problem persists, Contact Dell .
TIME-OF-DAY NOT SET-PLEASE RUN THE SYSTEM SETUP PROGRAM	The time or date stored in the system setup program does not match the system clock. Correct the settings for the Date and Time options.
TIMER CHIP COUNTER 2 FAILED	A chip on the system board may be malfunctioning. Run the System Set tests in Dell Diagnostics .
UNEXPECTED INTERRUPT IN PROTECTED MODE	The keyboard controller may be malfunctioning, or a memory module may be loose. Run the System Memory tests and the Keyboard Controller test in Dell Diagnostics or Contact Dell .
X:\ IS NOT ACCESSIBLE. THE DEVICE IS NOT READY	Insert a disk into the drive and try again.

System error messages

Table 7. System error messages

System message	Description
Alert! Previous attempts at booting this system have failed at checkpoint [nnnn]. For help in resolving this problem, please note this checkpoint and contact Dell Technical Support	The computer failed to complete the boot routine three consecutive times for the same error.
CMOS checksum error	RTC is reset, BIOS Setup default has been loaded.
CPU fan failure	CPU fan has failed.
System fan failure	System fan has failed.
Hard-disk drive failure	Possible hard disk drive failure during POST.
Keyboard failure	Keyboard failure or loose cable. If reseating the cable does not solve the problem, replace the keyboard.
No boot device available	No bootable partition on hard disk drive, the hard disk drive cable is loose, or no bootable device exists.

System message**Description**

No timer tick interrupt

NOTICE - Hard Drive SELF MONITORING SYSTEM has reported that a parameter has exceeded its normal operating range. Dell recommends that you back up your data regularly. A parameter out of range may or may not indicate a potential hard drive problem

- If the hard drive is your boot device, ensure that the cables are connected and that the drive is installed properly and partitioned as a boot device.
- Enter system setup and ensure that the boot sequence information is correct.

A chip on the system board might be malfunctioning or motherboard failure.

S.M.A.R.T error, possible hard disk drive failure.

Getting help

Contacting Dell

① **NOTE:** If you do not have an active Internet connection, you can find contact information on your purchase invoice, packing slip, bill, or Dell product catalog.

Dell provides several online and telephone-based support and service options. Availability varies by country and product, and some services may not be available in your area. To contact Dell for sales, technical support, or customer service issues:

- 1 Go to **Dell.com/support**.
- 2 Select your support category.
- 3 Verify your country or region in the **Choose a Country/Region** drop-down list at the bottom of the page.
- 4 Select the appropriate service or support link based on your need.